#### $MINI\ COBRA^{\mathsf{TM}}\ UPDATE$

Presented by: Donald Wayne Brown

Director, Probe Card Division

Prepared by: Anthony Paul Martel

Sr. R&D Technician



# REDUCED PAD PITCH COBRA MINI COBRA™

#### MINI COBRA™

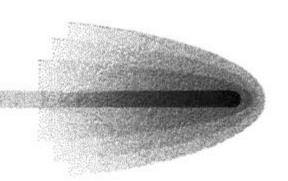
- 100μ Pitch, Peripheral
- 105µ Minimum Pitch, Multi-Dut
- 120µ Matrix



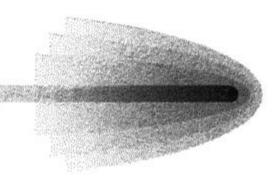
#### Beta Device

- 100μ Pitch
- · Contact 2.5 mil dia.
  - Pointed Tip
- Peripheral
- 100 mA per Contact (Continuous)
- Aluminum Bond Pads





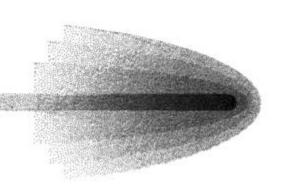
#### IMPACT MARKS



- Contacts Touching on Aluminum Wafer
  - 5 Mils. Overdrive from First Touch Down
  - Impact Measures .0003 in Diameter
  - Minimum Pad Damage



#### LASER DRILLING

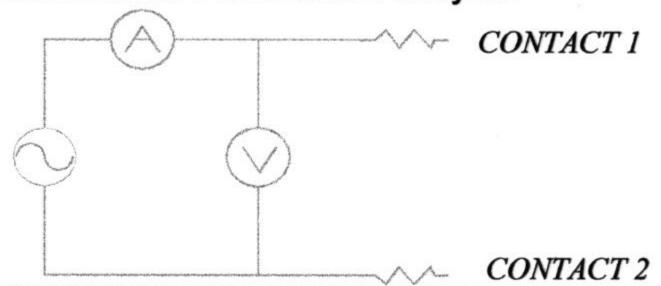


 Laser Machining used to Provide Micro Holes for Probe Contacts



# LEAKAGE TEST RESULTS of MATERIAL "A"

 The measurements were taken with a Hewlett-Packard model 4156A Semiconductor Parameter Analyzer

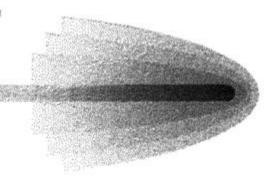


### FORCE Vs DEFLECTION

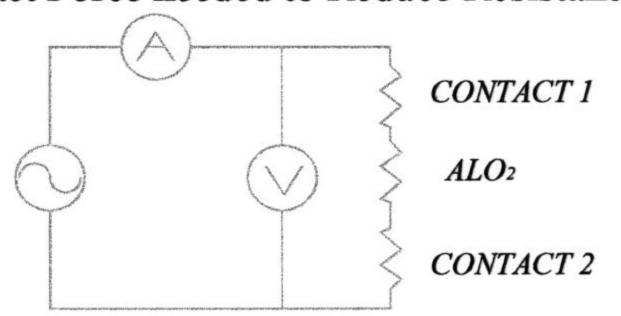
- Working Area of Contact is 3-5 Mils Deflection
- 5 Mils Deflection Delivers 10-12 Grams



#### RESISTANCE Vs TIME



- Path/System Resistance of 2 Contacts
- Contact Force needed to Reduce Resistance



### MINI COBRA SPECIFICATIONS

- Temperature Range 0-85°C
- Impact Accuracy- ± 12.5μ
- Life 250K Touch Downs
- Planarity Pointed <.003" Flat <.00075"</li>
- Field Repairability Yes
- Current Carrying Capability 200 mA

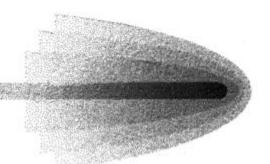


#### FAILURE MODES



- due to Excessive Current
- MELTING of CONTACTS
- EXCEEDING YIELD STRENGTH of CONTACTS
  - Over Travel 8 Mils.
- OVERHEATING of CONTACTS
  - Affects on Yield Strength/Gram Force
  - Contact Arcing/Welding
  - Increase in Frictional Forces
  - Inadequate Overdrive to Penetrate
    - Wafer Oxidation
    - Dielectric Residues
    - Organic Films





### WHAT'S NEXT?

- Space Transformer Development
  - Flex
  - MLC
- 135 °C Temperature Probing



### THANKS FOR LISTENING!



